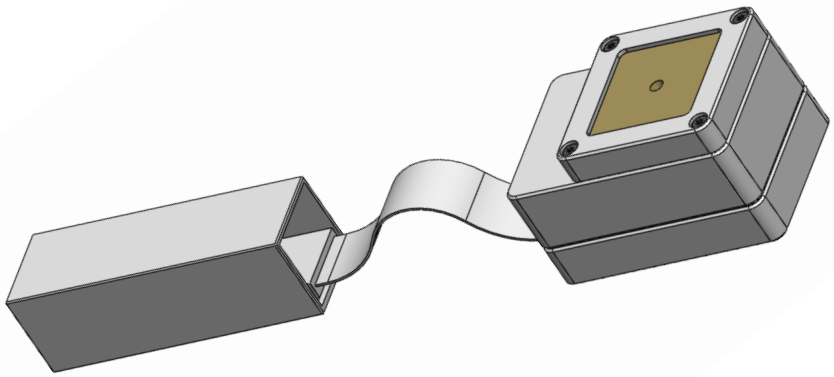
ADVACAM
Imaging the Unseen

MiniPIX GAMMA



Datasheet

General features

The **MiniPIX GAMMA** is a miniaturized and low power radiation camera with shielding box equipped with particle tracking and imaging detector Timepix3 (256 x 256 square pixels with pitch of 55 µm). The system is available with a 1000 µm thick CdTe sensor.

The Timepix3 detector is position, energy and time sensitive: For each ionizing particle (e.g. X-ray photon) it digitally registers its position, energy, time of arrival and track shape - basically all information you could want. The other measures can be calculated from the track shape (particle type, direction of flight, LET, charge...). The information on each detected particle is either read out immediately (pixel mode) at maximal rate of 2,3 million hit pixels per second or accumulated in images (frame mode) and read out later at maximal speed of 16 frames per second.

The typical and intended applications of **MiniPIX GAMMA** are:

- **Medical application:** SPECT imaging
- **Non-destructive testing:** Backscatter imaging
- **Material analysis:** XRF imaging
- **Radiation monitor[1]:** Particle type sorting, spectroscopy, directional sensitivity.

The **MiniPIX GAMMA** device is controlled via USB 2.0 interface with standard µUSB connector. Complex PIXet Pro software for detector operation is provided together with the device. All major operating systems are supported (MS Windows, Mac OS and LINUX).

Main Features

- Readout chip type Timepix3
- Pixel size[2] ..... 55 x 55 µm^2
- Sensor resolution ..... 256 x 256 pixels
- Time resolution ..... 1,6 ns
- Dynamic range in one frame[3] 1022
- Sensor material ..... 1000 µm CdTe
- Dark current ..... none
- Interface ..... USB 2.0 (High-Speed)
- Maximum readout speed ..... 2,35 million pixels / s

[1] The device is not certified dosimeter. It serves as the first level indicator and monitor of radiation fields allowing identification of a radiation type. Radiation protection of people cannot be based on measurements with this device.
[2] 55 x 110 µm^2 at the edges and 110 x 110 µm^2 at the corners
[3] i.e. counter depth. Dynamic range of integrated picture is theoretically unlimited.

Device parameters

Operation conditions

Symbol	Parameter	Value	Units	Comment
T_a	Operating ambient temperature range[1]	0-50	°C	
Φ	Humidity	< 80	%	Not condensing
IP	IP rating with cover	IP20		For transport purposes
IP	IP rating without cover	IP00		

[1] With temperature stabilization – see the paragraph below.



- The device will automatically shut down after chip or CPU temperature exceeds 55 °C.
- Intended for dust free indoor use.
- A direct connection to the host device is required for maximum performance. Connecting via a USB hub may negatively affect the performance and stability of the device.

External temperature stabilization

Temperature stabilization of the device is strongly recommended for consistent results. Attaching a Peltier cooling or cooling plate at the back of the detector should serve the purpose. The temperature should be set to 22 °C.

Electrical specification

T_{dev} = 22 °C, USB voltage V_{CC} = 4,8 V

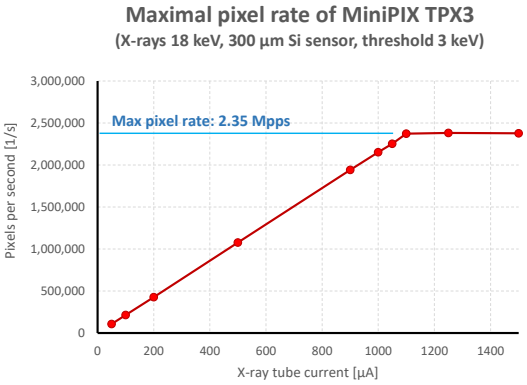
Symbol	Parameter	Min	Typ	Max	Units	Comment
V_{CC}	Supply Voltage	4,0	5,0	5,5	V	Comply with USB 2.0
I_{CC}	Chip active		300	500	mA	Comply with USB 2.0, Mode dependent
P1	Power consumption			2,5	W	

Performance characteristics

Symbol	Parameter	Min	Typ.	Max	Units	Comment
f_f	Frame-rate			16	fps	with USB 2.0 Host
T_{FREAD}	Frame readout time	62			ms	
f_p	Pixel type hit-rate in ToT+ToA mode (pixels per second)			2,35 x 10^6	pps	with USB 2.0 Host

Pixel mode hit-rate measurement

The whole detector is exposed to homogenous direct (perpendicular) irradiation from X-ray tube operated at 18 kVp with 2 mm Aluminum filter. The measurement type is set to "**Pixels**" and mode to "**ToT+ToA**", all other parameters are set to factory defaults (as stored in configuration file delivered with the device). The exposure time is set to 0,1 s. The "Clustering" tool of PIXet Pro is used to analyze measured data. The number of hit pixels per second is drawn as function of X-ray tube current searching for saturation.



Sensor parameters

T_{dev} = 22 °C

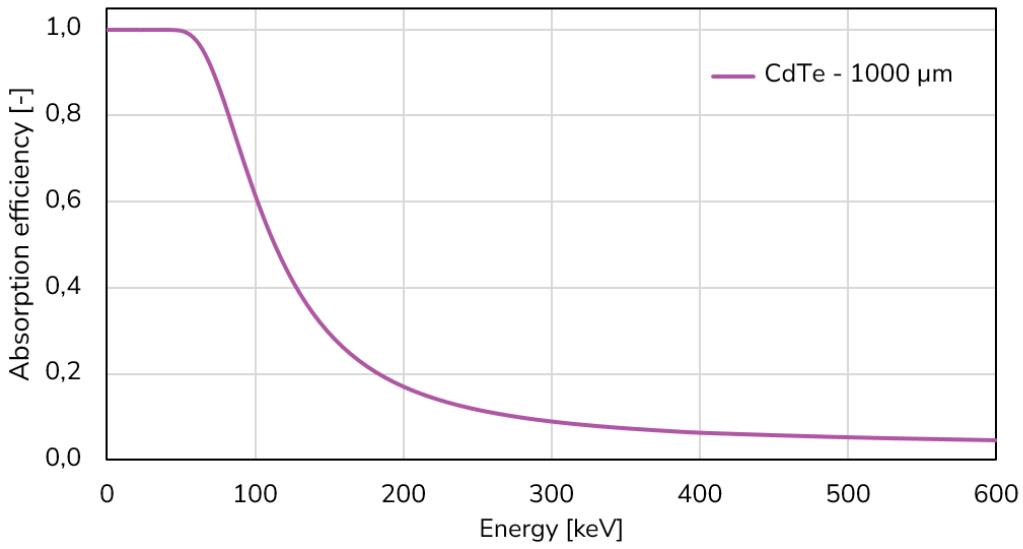
Parameter	CdTe	Units	Comment
Thickness	1000	µm	
Calibrated energy threshold[2]	5,0	keV	
Typical bias voltage	-450	V	
Energy resolution in ToT mode (σ @ 60 keV)	2,8 – 5,4	keV	Valid for the standard calibration
Energy resolution in ToT mode (σ @ 122 keV)	3,4 – 6,0	keV	Valid for the standard calibration
Typical detectable energy range for X-rays	5 – 500	keV	See chart below
Good pixels	> 99,5 %		

[1] Customized product

[2] Premium calibration and/or chip class can achieve even better performance. For more information, please contact support@advacam.cz

[3] 55 x 110 µm at the edges and 110 x 110 µm at the corners

Absorption efficiency for photons



Basic principles, measurement types and operational modes

The ionizing radiation particle interacts with the sensor material creating an electric charge. This charge is collected by electric field and brought to pixel preamplifier where it is amplified and shaped forming triangular voltage pulse. The amplitude and duration of this pulse is proportional to energy deposited by particle within the pixel. The situation when the voltage pulse amplitude in particular pixel exceeds preselected threshold value is called “event” or “hit”.

Each pixel contains three digital counters (10, 14 and 4 bits). These counters are used differently according to measurement type and mode. There are four different quantities which can be measured and stored in counters of each pixel – these are selected by operational modes.

Operational modes:

Number of events	= number of events (hits) in the pixel during exposure time (this mode is suitable mainly for frame type readout).
Time-**o**ver-**T**hreshold (ToT)	= number of periods of 40 MHz clock signal (25 ns step) when amplifier output signal stays over the energy threshold. The ToT can be transformed to energy in keV using per-pixel-calibration function. The coefficients for per-pixel-calibration are unique for each pixel and they are stored in configuration file delivered with the device. The energy calibration is valid only for given values of other detector parameters as delivered in configuration file (especially threshold)
Time-**o**f-**A**rrival (ToA)	= number of periods of 40 MHz clock signal (25 ns step) from start of exposure till the event is registered by pixel (i.e. pulse in pixel crosses the threshold). The range is 409,6 µs. Additional 16 bits are added in FPGA in readout electronics so that the total range is 26,8 seconds. An additional counter has also been added to perform scans beyond 26,8 seconds.
Fast-**T**ime-**o**f-**A**rrival (FToA)	= time difference between event detection and next clock signal measured with step of 1,5625 ns. Range is 4 bits. The combination of ToA and FToA gives precise time of event detection in nanoseconds using following formula:

$$\text{Time [ns]} = \text{ToA}*25 - \text{FToA}*1{,}5625$$

Measurement types:

Frame type measurement — No data is sent out of device during the exposure time. All measured events are accumulated in counters of pixels. **Event counter** is incremented and ToT is integrated in to **iToT counter** for all events. The measured data is read-out after end of exposure time for all pixels with nonzero content. No measurement can be performed during readout process. Measurement types in PIXet Pro: Frames, Integral.

Pixel type measurement — Information about all hit pixels is read-out immediately and continuously during exposure time. If hit rate is below maximal value (see f_p in table of Performance characteristics) then there is practically no deadtime. Measurement type in PIXet Pro: Pixels.

Sometimes this mode is referred to as the data-driven mode or the event-based mode.

Combinations of operation modes and measurement types (rarely used cases are shown with gray background):

Type	Mode	Range	Description
Frames (reading all pixels after end of exposure)	ToA+ToT	18 bit + 10 bit	2 output frames per exposure: ToA = Time of Arrival of first event in pixel, ToA and FToA[1] combined ToT = Time over Threshold, i.e. energy in keV if calibration is loaded and switched on
	ToA	18 bit	1 output frame: ToA = Time of Arrival of first event in pixel, ToA and FToA[1] combined
	Event+iToT	10 bit + 14 bit	2 output frames per exposure: Events = number of events in pixel iToT = integrated Time over Threshold, i.e. energy in keV if calibration is loaded and switched on, for all events in pixel
Pixels (reading only hit pixels continuously during exposure)	ToA+ToT	18 bit + 10 bit	Data stream contains 4 values per pixel per event: Position, ToT, ToA and FToA[1] (for data formats .t3*)
	ToA	18 bit	Data stream contains 3 values per pixel per event: Position, ToA and FToA[1] (for data formats .t3*)
	Only ToT	10 bit	Data stream contains 2 values per pixel per event: Position and ToT (for data formats .t3*)

[1] ToA and FToA are combined together by software automatically. For Pixel type measurement, if saved as a .t3pa file, ToA and FToA are stored as separate items

Device description

The device is delivered with USB flash disk containing installer of PIXet Pro software, unique device configuration and calibration file and protocol on quality tests.
The device casing is made of aluminum with sliding cover made of stainless steel protecting the sensor window. The communication and powering is provided by USB 2.0 Micro-B connector and cable.

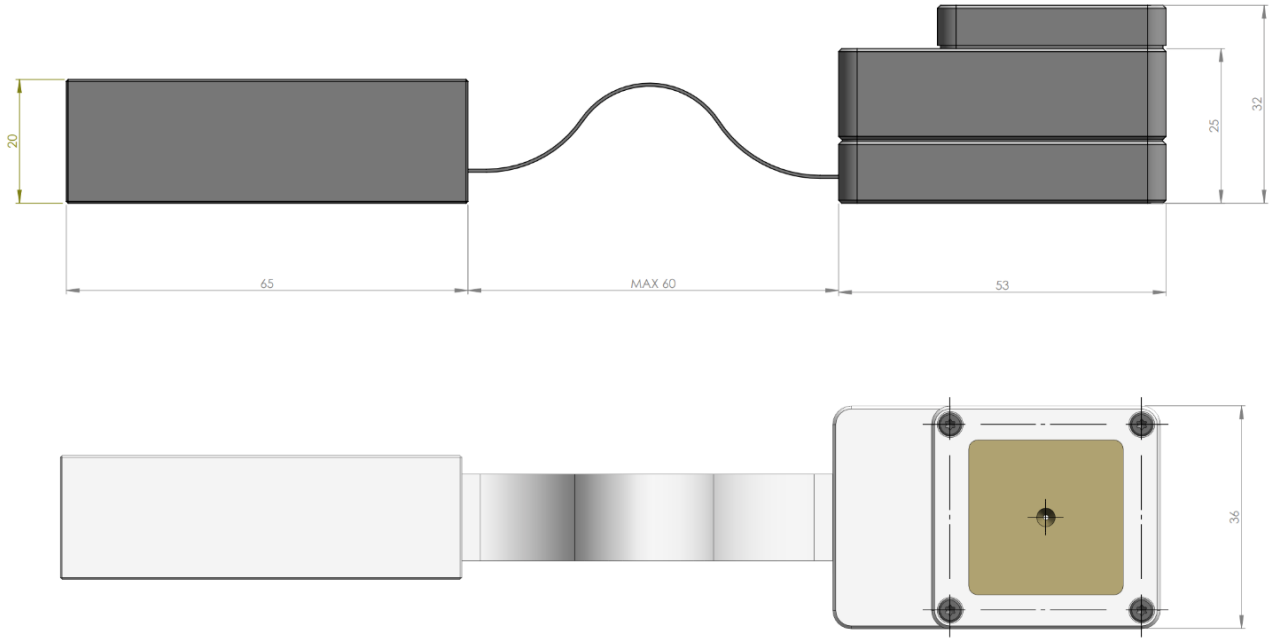


High voltage - Sensor chip is supplied with high voltage up to -500 V. To avoid sparks or unwanted discharge follow EN 61010-1 (chapter 6.7, Insulation requirements. Fig. 4, Tab. 6, Annex C).

USB connector

USB type Micro-B, Standard USB 2.0 High-Speed. The USB cable length should be less than 2m. For longer connections, a repeater or active cable is suggested.

Mechanical dimensions

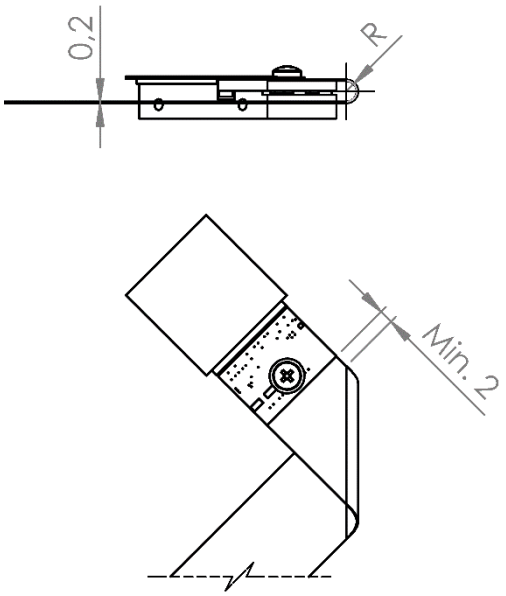


All dimensions are in mm.

Parameter	Value[1]	Units	Comment
Collimator thickness	3	mm	
Pinhole diameter	0,4	mm	
Pinhole opening angle	40	°	
Distance Pinhole to sensor top	17,46	mm	
Shielding thickness	3	mm	Wolfram alloy
Max energy for shielding efficiency 99 %	150	keV	

[1]Standard values, customization on request.

Flex cable bending parameters



Bending radius according to IPC-2223 standard (2 layers flex PCB, 0,2 mm thick)

Bending type	Stable	Semi-Dynamic	Dynamic
Min. bending radius	2 mm	4 mm	30 mm

Instructions for safe use

- Proper heatsink attached to an aluminum sensor support,
- Mechanical cover of the whole device,

To avoid malfunction or damage to your **MiniPIX GAMMA** please obey the following:

- Do not expose to water or moisture.
- Do not disassemble. Wire-bonding connection may be irreversibly damaged.
- Do not insert any object into the sensor window.
- The maximum USB cable length is 2 m.
- Thermal stabilization of the device is necessary. Recommended temperature is 22 °C.
- A direct connection to the host device is required for maximum performance. Connecting via a USB hub may negatively affect the performance and stability of the device.
- The protection provided by this product may be impaired if it is used in a manner not described in this document.

Disposal



Do not dispose these instruments as unsorted municipal waste. Please use separate collection facility to contact the supplier from which the instrument was purchased. Please make sure discarded electrical waste is properly recycled to reduce environmental impact.

Release history

Date (YY/MM/DD)	Changes	Changed by
26/10/01	Preliminary datasheet	

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